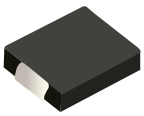
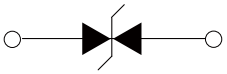
FEATURES

- Low profile package
- Ideal for automated placement
- 5000 Watt peak pulse power capability with a 10/1000μs waveform
- For surface mounted applicatons to optimize board space
- Excellent clamping capability
- Very fast response time
- Low incremental surge resistance



DO-214AB(SMC)



Schematic Symbol

APPLICATIONS

- Power supply protection
- Automotive application
- Industrial application
- Power management

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS (T_A=25°C)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation on 10/1000μs waveform (Note1, Note2).	P_{PPM}	5000	Watts
Steady State Power Dissipation at T_L=50°C,Lead lengths.375”(9.5mm) (Note2)	P_D	6.5	Watts

Notes : 1.Non-repetitive current pulse,T_A=25°C.
2.Mounted on 5.0mm*5.0mm (0.03mm thick) Copper Pads to each terminal.

THERMAL CONSIDERATIONS

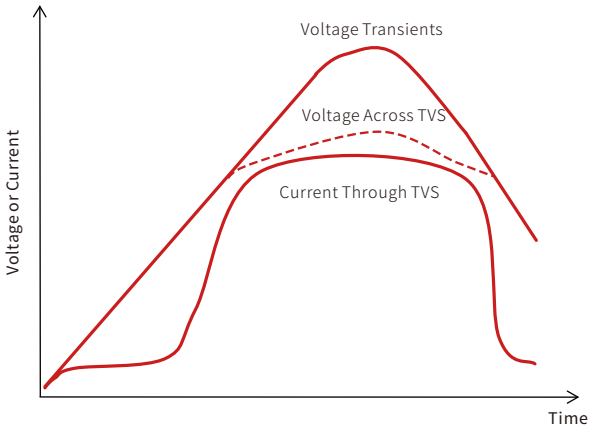
Parameter	Symbol	Value	Unit
Operating Junction Temperature	T_J	-55 to +150	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C
Junction to Ambient on printed circuit	$R_{\theta JA}$	75	°C/W

ELECTRICAL CHARACTERISTICS (T_A=25℃)

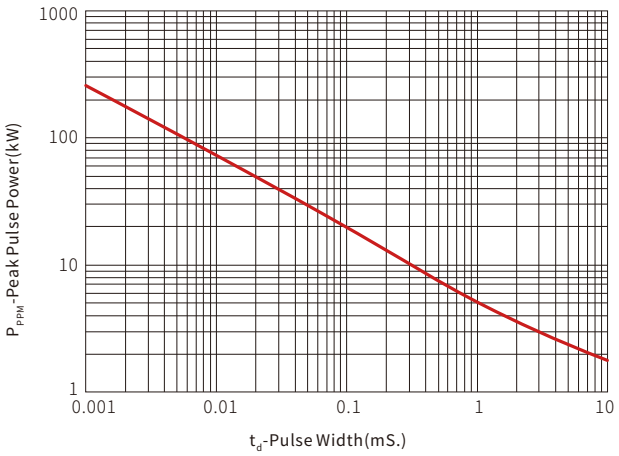
Part Number	Device Marking Code	Reverse Stand-off Voltage	Breakdown Voltage Min.@I_T	Breakdown Voltage Max.@I_T	Test Current	Maximum Clamping Voltage @I_{PP}	Peak Pulse Current	Reverse Leakage @V_{RWM}
		V_{RWM}(V)	V_{BR}(V)	V_{BR}(V)	I_T(mA)	V_C(V)	I_{PP}(A)	I_R(uA)
SVC500B130	5BHK	130.0	144.0	159.0	1.0	209.0	24.0	5.0

CHARACTERISTIC CURVES

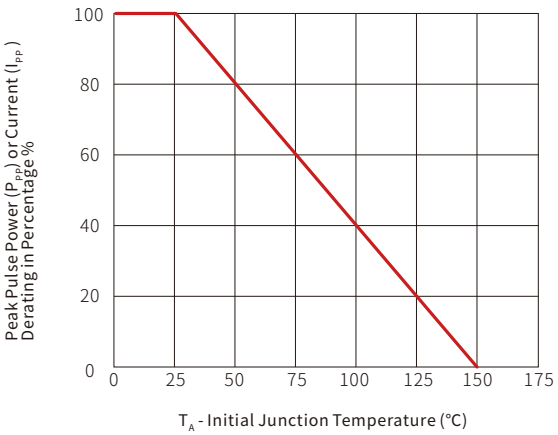
TVS Transients Clamping Waveform



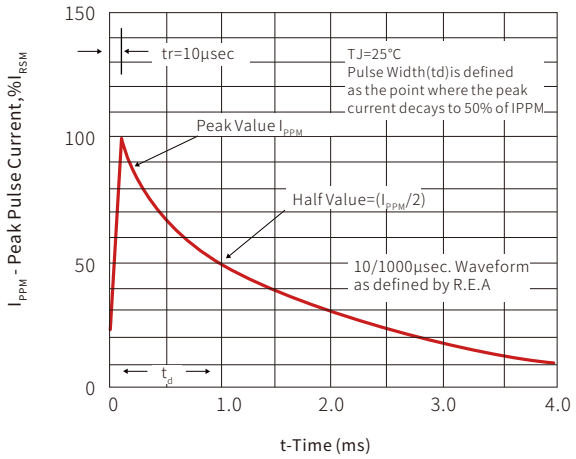
Peak Pulse Power Rating Curve



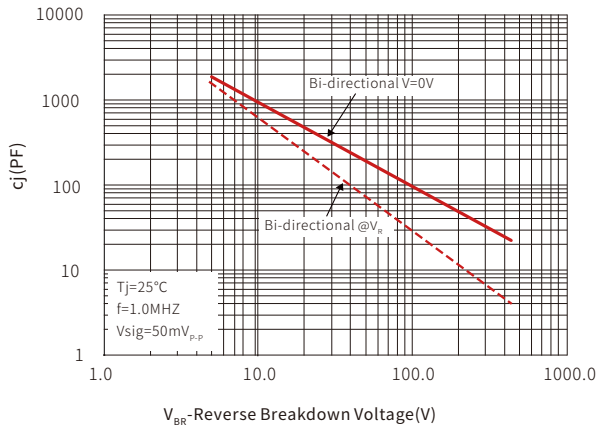
Pulse Derating Curve



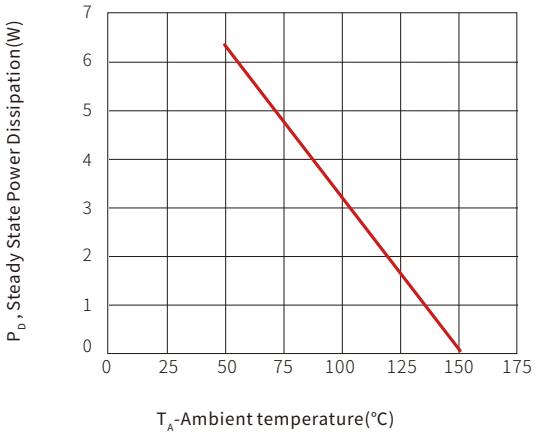
Pulse Waveform



Typical Junction Capacitance

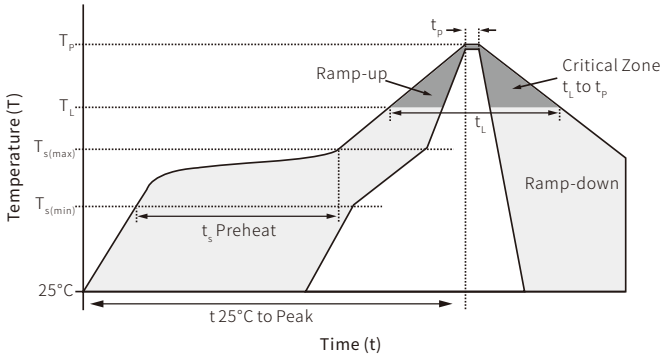


Steady State Power Dissipaton Deraiting Curve

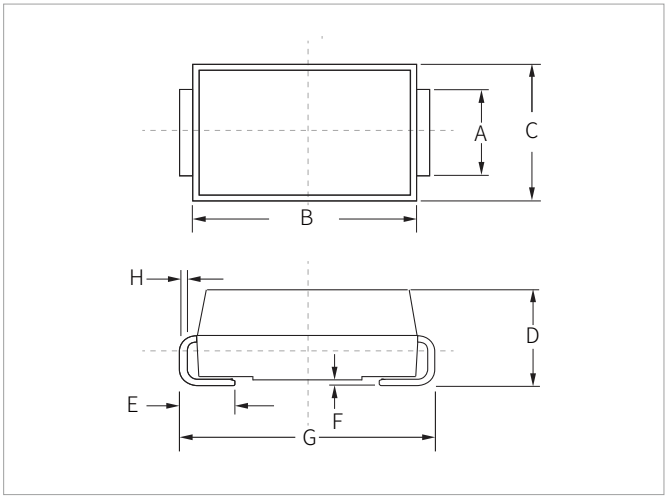


SOLDERING PARAMETERS

Reflow Condition		Lead–free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

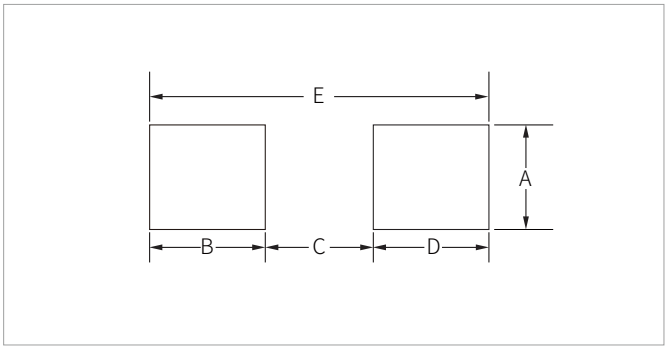


DO-214AB(SMC) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.80	3.20	0.110	0.126
B	6.60	7.20	0.260	0.283
C	5.70	6.10	0.224	0.240
D	2.15	2.75	0.085	0.108
E	1.00	1.60	0.039	0.063
F	0.02	0.20	0.000	0.008
G	7.60	8.00	0.299	0.315
H	0.15	0.30	0.006	0.012

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	-	0.129	-
B	2.40	-	0.094	-
C	-	4.20	-	0.165
D	2.40	-	0.094	-
E	8.20REF		0.323REF	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SVC500B130	DO-214AB(SMC)	3000PCS	13"

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